

# SOT1462-1

plastic thermal enhanced quad flat package; no leads; 20 terminals; body 8.0 mm x 8.0 mm x 2.1 mm

23 September 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	HQFN
<b>Package type industry code</b>	HQFN20
<b>Package style descriptive code</b>	HQFP
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	12-10-2015

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	7.9	-	8	8.1	mm
E	package width	7.9	-	8	8.1	mm
A	seated height	2	-	2.1	2.2	mm
e	nominal pitch	-	-	1.15	-	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	

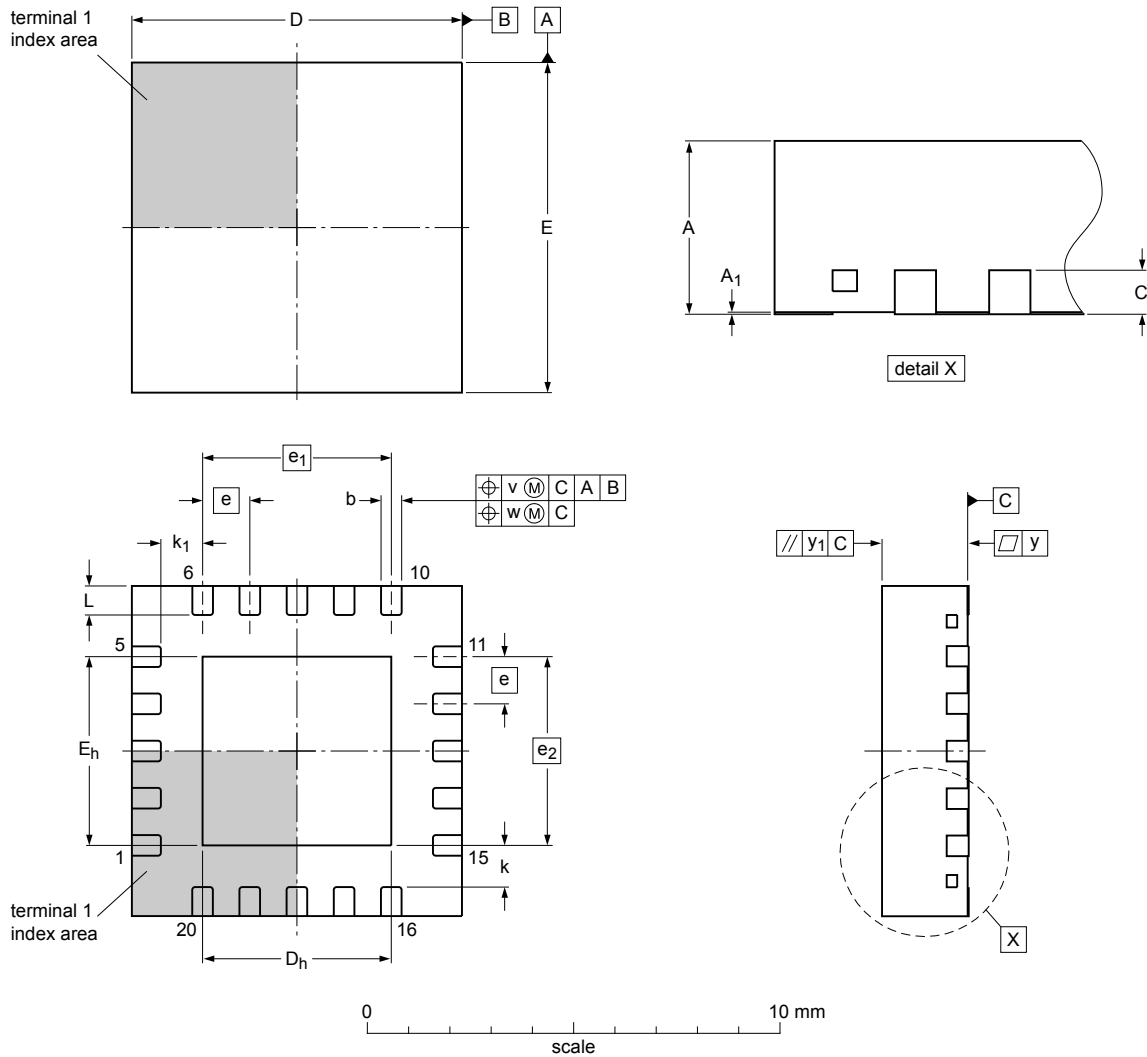


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## 2. Package outline

HQFN20: plastic thermal enhanced quad flat package; no leads; 20 terminals; body 8.0 x 8.0 x 2.1 mm

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Dimensions (mm are the original dimensions)

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	C	D <sup>(1)</sup>	D <sub>h</sub>	E <sup>(1)</sup>	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	k	k <sub>1</sub>	L	v	w	y	y <sub>1</sub>
max	2.20	0.05	0.60		8.1	4.72	8.1	4.72						0.8				
mm nom	2.10		0.50	0.538	8.0	4.62	8.0	4.62	1.15	4.6	4.6	0.99	0.99	0.7	0.1	0.05	0.1	0.1
min	2.00	0.00	0.40		7.9	4.52	7.9	4.52						0.6				

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

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Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1462-1					-15-09-14- 15-10-12

Fig. 1. Package outline HQFN20 (SOT1462-1)

plastic thermal enhanced quad flat package; no leads; 20 terminals; body 8.0 mm x 8.0 mm x 2.1 mm

### 3. Legal information

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